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Amendments to the Claims

1. (Currently amended) A method of joining two silicon parts, comprising plasma spraying silicon across a seam separating said two silicon parts to form a coating on adjacent surface areas of said two silicon parts, wherein the silicon parts are juxtaposed during the plasma spraying step with the seam separating them and wherein the plasma spraying coats silicon onto both of the silicon parts.
2. (Original) The method of Claim 1, wherein the parts are subjected to atmospheric pressure during said plasma spraying.
3. (Original) The method of Claim 1, wherein portions of the parts adjacent the seam are held at a temperature of no more than 500°C.
4. (Original) The method of Claim 3, wherein said temperature is no more than 200°C.
5. (Original) The method of Claim 1, wherein said plasma spraying includes injecting silicon powder into a plasma of a gas.
6. (Original) The method of Claim 5, wherein said powder comprises particles having diameters in a range of 15 to 45µm.
7. (Original) The method of Claim 5, wherein said powder comprises particles of virgin polysilicon.
8. (Currently amended) ~~The method of Claim 1~~ A method of joining two silicon parts,

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comprising plasma spraying silicon across a seam separating said two silicon parts to form a coating on adjacent surface areas of said two silicon parts, wherein principal surfaces of said two parts are perpendicular to each other at said seam.

9. (Currently amended) ~~The method of Claim 8~~ A method of joining two silicon parts, comprising plasma spraying silicon across a seam separating said two silicon parts to form a coating on adjacent surface areas of said two silicon parts, wherein at least one of said parts is preformed with a bevel adjacent to said seam.

10. (Previously presented) The method of Claim 9, wherein a first one of the parts is preformed with said bevel and a second one of the parts does not have a bevel adjacent to said seam.

11. (Previously presented) The method of Claim 1, wherein at least one of said parts is preformed with a bevel adjacent to said seam.

12. (Currently amended) ~~The method of Claim 1~~ A method of joining two silicon parts, comprising plasma spraying silicon across a seam separating said two silicon parts to form a coating on adjacent surface areas of said two silicon parts, wherein a first one of said parts includes a hole and a second one of said parts is disposed within said hole and wherein said plasma spraying forms respective silicon layers contacting said first and second parts on opposite ends of said hole.

13 -26. (Canceled)

27. (Previously presented) A method of joining the parts of a silicon substrate support fixture comprising (a) first and second silicon bases each having mortise holes formed therein and (b) a plurality of legs comprising silicon, having teeth cut therein for supporting a plurality of

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substrates in parallel relationship, and inserted into said mortise holes to form respective seams between respective pairs of said bases and said legs, said method comprising the ~~[[step]]~~ steps of: assembling together the legs and bases, wherein the legs and bases are not fixed together at a beginning of the plasma spraying step but are fixed together at an end of the plasma spraying step; and then plasma spraying silicon across said seams to form layers of silicon bonded to said legs and bases across said seams.

28. (Previously presented) The method of Claim 27, performed in atmospheric pressure.

29. (Previously presented) The method of Claim 27, wherein portions of the parts adjacent the seams during said plasma spraying are held at a temperature of no more than 500°C.

30 – 32. (Canceled)

33. (Previously presented) The method of claim 1, wherein prior to the plasma spraying the two parts were juxtaposed but not fixed together and after the plasma spraying the coating fixes the parts together.

34. (Previously presented) A method of joining two silicon parts, comprising: juxtaposing the two silicon parts to form a seam separating the silicon parts; and plasma spraying a silicon layer onto adjacent areas of the juxtaposed silicon parts and across the seam, whereby the silicon layers fixes the two silicon parts together.

35. (Previously presented) The method of claim 34, wherein the parts are subjected to atmospheric pressure during the plasma spraying.

36. (Previously presented) The method of claim 35, wherein portions of the parts

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adjacent the seam are held at a temperature of no more than 500°C.

37. (Canceled)